

Tack Flux No-Clean for Low Temp in Jar 150g

Product Highlights

Ideal for all rework, solder, de-solder and reflow applications

Non-corrosive, non-conductive, no-clean

Tack flux will not run all over PCB when applied

Has a pleasant odor

Excellent wetting

Easily cleaned with isopropyl alcohol (IPA)

Attachment of BGA spheres

Soldering flip chip components

Long stencil life

Wide process window

Clear residue

Commonly used with Sn42/Bi58, Sn42/Bi57.6/Ag0.4, and Sn42/Bi57/Ag1 alloys, which melt at 138°C (281°F)

RoHS II and REACH compliant

Specifications

Flux Type:	Synthetic No-Clean (for low temperature applications)
Flux Classification:	RELO
Packaging:	Jar 150g
Shelf Life:	Refrigerated >24 months, Unrefrigerated >24 months

Stencil Life

>8 hours @ 20-50% RH 22-28°C (72-82°F)

>4 hours @ 50-70% RH 22-28°C (72-82°F)

Stencil Cleaning

Automated stencil cleaning systems for both stencil and misprinted boards. Manual cleaning using isopropyl alcohol (IPA).

Storage and Handling

Store refrigerated or at room temperature 3-25°C (37-77°F). Do not freeze. Allow 4 hours for flux to reach an operating temperature of 20-25°C (68-77°F) before use.

Conforms to the following Industry Standards:

J-STD-004B, Amendment 1 (Solder Fluxes):

Yes

RoHS 2 Directive 2011/65/EU:

Yes